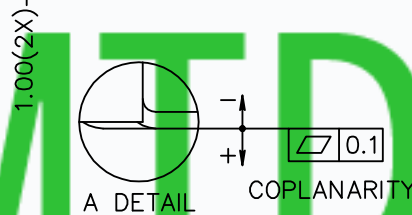
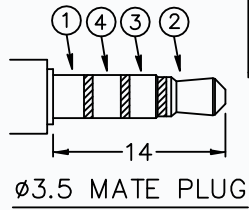
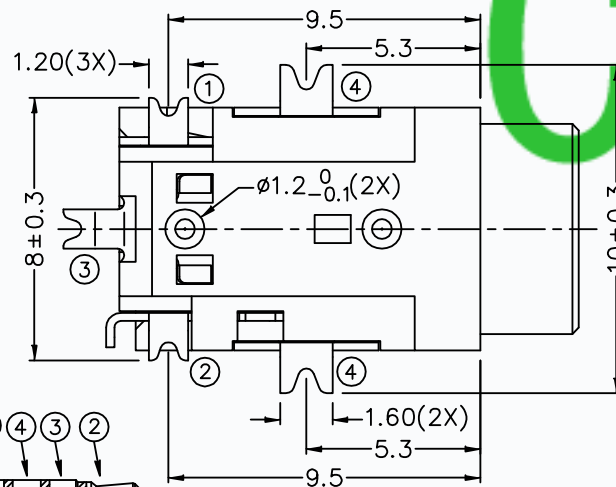
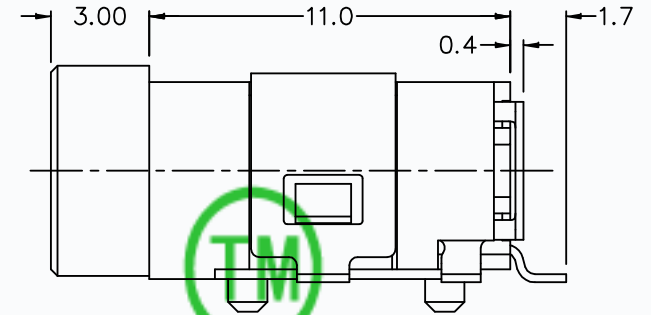
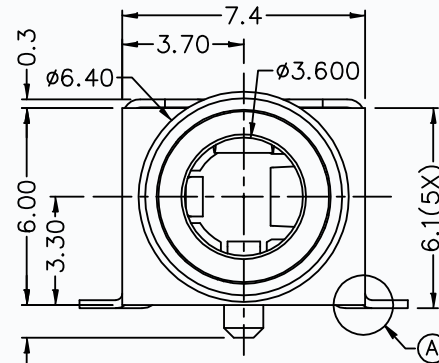
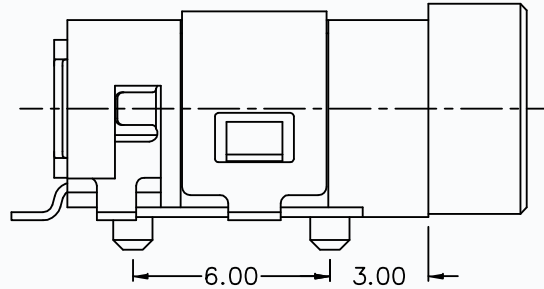
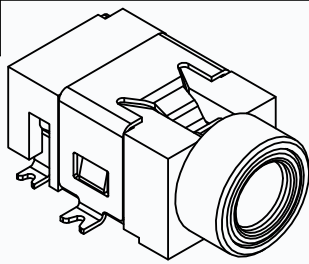


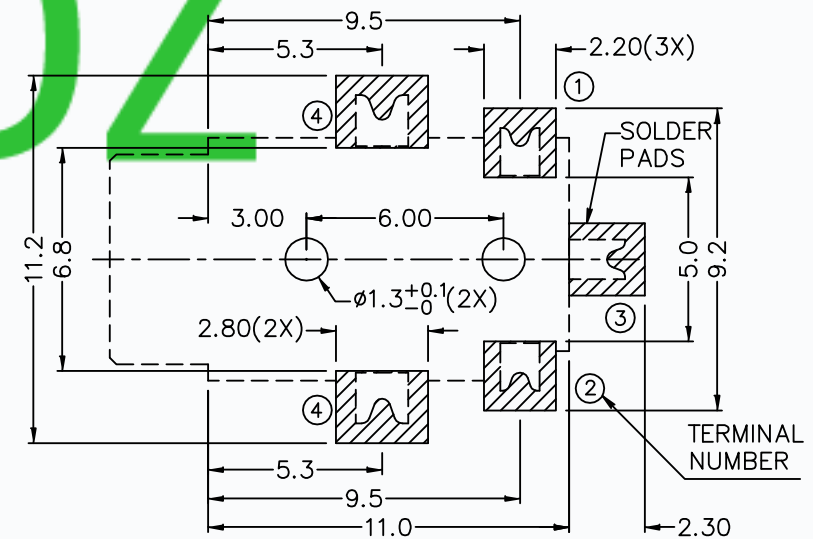
CAD FILE:



* MATERIAL

TERMINAL 1 : COPPER ALLOY
TERMINAL 2 : COPPER ALLOY
TERMINAL 3 : COPPER ALLOY
TERMINAL 4 : COPPER ALLOY
BUSHING : BRASS
HOUSING : PA6T

MODEL NO.	T13-3594DM	T13-3594DM-3
SCHEMATIC		

RECOMMENDED
SOLDER PAD LAYOUT

TOLERANCE
UNLESS SPECIFIED
WITHIN 1.5mm : ±0.1mm
OVER 1.5mm : ±0.2mm

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DONGGUAN TIANDU ELECTRONICS CO., LTD.

TITLE : 3.5mm SMD PHONE JACK

UNIT : mm

DRWG NO.: CMTDDZ-T13-3594DM-00

MODEL: T13-3594DM

SCALE: 3:1

DWN. ERIC 2013-6-17

CMTDDZ 东莞市田都电子有限公司
DONGGUAN TIANDU ELECTRONICS CO.,LTD.

CHK'D MAIKO 2013-6-17

APPD. DESCRIPTIONS OF REVISION

APPD. Coco 2013-6-17